



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD50P04P4L-11	Issued	17. February 2022
MA#	MA005699001		
Package	PG-TO252-3-313	Weight*	318.16 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.525	0.48	0.48	4793	4793
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		463	
	non noble metal	copper	7440-50-8	147.096	46.24	46.30	462336	462938
wire	non noble metal	aluminium	7429-90-5	2.688	0.84	0.84	8447	8447
encapsulation	inorganic material	zinc oxide	1314-13-2	1.407	0.44		4422	
	miscellaneous	miscellaneous	-	7.034	2.21		22110	
	plastics	epoxy resin	-	21.103	6.63		66329	
	inorganic material	silicon dioxide	60676-86-0	111.143	34.93	44.21	349332	442193
lead finish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11755	11755
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4465	4476
solder	non noble metal	tin	7440-31-5	0.032	0.01		101	
	noble metal	silver	7440-22-4	0.040	0.01		126	
	non noble metal	lead	7439-92-1	1.532	0.48	0.50	4817	5044
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60276	60354
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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